UPDATE CHANGE NOTIFICATION # 20303

Generic Copy

Issue Date: 24-Jun-2014

TITLE: Update Change Notification to IPCN20303 for Assembly and Test site change of MSOP8 package.

PROPOSED FIRST SHIP DATE: 24-Nov-2014

AFFECTED CHANGE CATEGORY(S): Assembly and Test site

ADDITIONAL RELIABILITY DATA:
Contact your local ON Semiconductor Sales Office or
<Satoru.Fujinuma@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or
<Takashi.Asami@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
<toshiitsu.igarashi@onsemi.com><takeshi2.hoshino@onsemi.com><shinya.okada@onsemi.com>
<naoki.koyama@onsemi.com>

NOTIFICATION TYPE:
Update Change Notification to IPCN

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

IPCN20303 announced MSOP8 package will be transferred by closing of Kanto Sanyo Semiconductor Co., Ltd (KSS) to SGC Industries Malaysia Sdn Bhd (SBN) and will be integrated with MICRO8 package.

However, as a result of having examined it again, MSOP8 will transfer it from KSS to ON Semiconductor SSMP Philippines Corporation.

As for this the materials and package outline of these products will remain identical. The product name does not change, too.

We apologize for any inconvenience this has caused.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

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QUALIFICATION PLAN:

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Test Items	Test Condition	Test Time
Temperature Humidity Bias ※	Ta=85dC, RH=85%, Vcc=Recommended	1000h
Temperature Cycle ※	Ta=-65dC(30min) ⇔ Ta=150dC(30min)	100Cycles
Pressure Cooker ※	Ta=121dC, RH=100%, 205kPa	96h
High Temperature Storage	Ta=150dC	1000h
Resistance to Soldering heat (Reflow soldering)	255dC,10s(Peak260dC)	2times

Notices: The test items with * mark are put into operation after the reflow soldering (at 255C for 10seconds MSL3)

Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

List of affected General Parts:

LV5113T-TLM-E
LV51130T-TLM-E
LV51131T-TLM-E